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INTERNATIONAL STANDARD

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

SEMICONDUCTOR DEVICES – MECHANICAL AND CLIMATIC TEST METHODS –

Part 3: External visual examination

FOREWORD

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International Standard IEC 60749-3 has been prepared by IEC technical committee 47: Semiconductor devices.

This second edition cancels and replaces the first edition published in 2002. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

a) reference to the need for ESD protection;
b) inclusion of information on the phenomenon of tin whiskers;
c) inclusion of an optional report form/checklist.

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